

# VIPER26

# Fixed frequency VIPer<sup>TM</sup> plus family

### Features

- 800 V avalanche rugged power section
- PWM operation with frequency jittering for low EMI
- Operating frequency:
  - 60 kHz for L type
  - 115 kHz for H type
- Standby power < 50 mW at 265 V<sub>AC</sub>
- Limiting current with adjustable set point
- On-board soft-start
- Safe auto-restart after a fault condition
- Hysteretic thermal shutdown

### Application

- Auxiliary power supply for appliances
- Power metering
- LED drivers
- SMPS for set-top boxes, DVD players and recorders



### Description

The device is an off-line converter with an 800 V avalanche ruggedness power section, a PWM controller, user defined overcurrent limit, protection against feedback network disconnection, hysteretic thermal protection, soft start up and safe auto restart after any fault condition.

Advance frequency jittering reduces EMI filter cost. Burst mode operation and the devices very low consumption both help to meet the standard set by energy saving regulations.

### Figure 1. Typical topology (V<sub>OUT</sub> ≤V<sub>DDCSon</sub>)



#### Table 1. Device summary

Order codes	Package	Packaging
VIPER26LN	DIP-7	Tube
VIPER26HN	DIF-7	Tube
VIPER26HD		Tube
VIPER26HDTR	SO16 narrow	Tape and reel
VIPER26LD	SOTO Harrow	Tube
VIPER26LDTR		Tape and reel

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## 1 Block diagram





## 2 Typical power

Table 2. Typica	al power
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Part number	2	30 V <sub>AC</sub>	85-265 V <sub>AC</sub>		
Farthumber	Adapter <sup>(1)</sup>	Open frame <sup>(2)</sup>	Adapter <sup>(1)</sup>	Open frame <sup>(2)</sup>	
VIPER26	18 W	20 W	10 W	12 W	

1. Typical continuous power in non ventilated enclosed adapter measured at 50  $^\circ\text{C}$  ambient.

2. Maximum practical continuous power in an open frame design at 50  $^\circ\text{C}$  ambient, with adequate heat sinking.



## 3 Pin settings





Note: The copper area for heat dissipation has to be designed under the DRAIN pins.

Pin n.		Name	Function
DIP-7	SO16		
1			Connected to the source of the internal power MOSFET and controller ground reference.
-	4	N.A.	Not available for user. It can be connected to GND (pins 1-2) or left not connected.
2	5	VDD	Supply voltage of the control section. This pin provides the charging current of the external capacitor.
3	6	LIM	This pin allows setting the drain current limitation. The limit can be reduced by connecting an external resistor between this pin and GND. Pin left open if default drain current limitation is used.
4	7	FB	Inverting input of the internal trans conductance error amplifier. Connecting the converter output to this pin through a single resistor results in an output voltage equal to the error amplifier reference voltage (See $V_{FB\_REF}$ on <i>Table 7</i> ). An external resistors divider is required for higher output voltages.
5	8	COMP	Output of the internal trans conductance error amplifier. The compensation network have to be placed between this pin and GND to achieve stability and good dynamic performance of the voltage control loop. The pin is used also to directly control the PWM with an optocoupler. The linear voltage range extends from $V_{COMPL}$ to $V_{COMPH}$ ( <i>Table 7</i> ).
7,8	13-16	DRAIN	High voltage drain pin. The built-in high voltage switched start-up bias current is drawn from this pin too. Pins connected to the metal frame to facilitate heat dissipation.

#### Table 3. Pin description

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# 4 Electrical data

## 4.1 Maximum ratings

Symbol Pin (DIP-7)		Parameter		lue	Unit
				Max	Onit
V <sub>DRAIN</sub>	7, 8	Drain-to-source (ground) voltage		800	V
E <sub>AV</sub>	7, 8	Repetitive avalanche energy (limited by $T_J = 150 \text{ °C}$ )		5	mJ
I <sub>AR</sub>	7, 8	Repetitive avalanche current (limited by $T_J = 150 \ ^\circ C$ )		1.5	А
I <sub>DRAIN</sub>	7, 8	Pulse drain current (limited by $T_J = 150 \text{ °C}$ )		3	А
V <sub>COMP</sub>	5	Input pin voltage	-0.3	3.5	V
V <sub>FB</sub>	4	Input pin voltage	-0.3	4.8	V
V <sub>LIM</sub>	3	Input pin voltage	-0.3	2.4	V
V <sub>DD</sub>	2	Supply voltage	-0.3	Self limited	V
I <sub>DD</sub>	2	Input current		20	mA
Р		Power dissipation at $T_A < 40 \text{ °C}$ (DIP-7)		1	W
P <sub>TOT</sub>		Power dissipation at $T_A < 60 \text{ °C}$ (SO16N)		1.5	W
TJ		Operating junction temperature range	-40	150	°C
T <sub>STG</sub>		Storage temperature	-55	150	°C

### Table 4. Absolute maximum ratings

### 4.2 Thermal data

#### Table 5. Thermal data

Symbol	Parameter	Max	Unit	
Symbol	r arameter		DIP-7	Onit
R <sub>thJP</sub>	Thermal resistance junction pin (Dissipated power = 1 W)	25	35	° C/W
R <sub>thJA</sub>	Thermal resistance junction ambient (Dissipated power = 1 W)	60	100	° C/W
R <sub>thJA</sub>	Thermal resistance junction ambient <sup>(1)</sup> (Dissipated power = 1 W)	50	80	° C/W

1. When mounted on a standard single side FR4 board with 100  $\text{mm}^2$  (0.155 sq in) of Cu (35  $\mu\text{m}$  thick)



### 4.3 Electrical characteristics

(T<sub>J</sub> = -25 to 125 °C, V<sub>DD</sub> = 14 V  $^{(a)}$ ; unless otherwise specified)

Symbol	Parameter	Test condition	Min	Тур	Max	Unit
V <sub>BVDSS</sub>	Break-down voltage	$I_{DRAIN} = 1 \text{ mA},$ $V_{COMP} = GND, T_J = 25 \text{ °C}$	800			V
I <sub>OFF</sub>	OFF state drain current $V_{DRAIN}$ = max rating, $V_{COMP}$ = GND				60	μA
D	Drain-source on state	I <sub>DRAIN</sub> = 0.2 A, T <sub>J</sub> = 25 °C			7	Ω
R <sub>DS(on)</sub>	resistance	I <sub>DRAIN</sub> = 0.2 A, T <sub>J</sub> = 125 °C			14	Ω
C <sub>OSS</sub>	Effective (energy related) output capacitance	V <sub>DRAIN</sub> = 0 to 640 V		40		pF

### Table 6.Power section

#### Table 7. Supply section

Symbol	Parameter	Test condition	Min	Тур	Max	Unit
Voltage						
V <sub>DRAIN_START</sub>	Drain-source start voltage		60	80	100	V
I <sub>DDch1</sub>	Charging current during the start up	$V_{DRAIN} = 100 \text{ V to } 640 \text{ V},$ $V_{DD} = 4 \text{ V}$	-0.6		-1.8	mA
I <sub>DDch2</sub>	Charging current during the autorestart	$V_{DRAIN} = 100 V \text{ to } 640 V,$ $V_{DD} = 9 V \text{ falling edge}$	-7		-13	mA
V <sub>DD</sub>	Operating voltage range		11.5		23.5	V
V <sub>DDclamp</sub>	V <sub>DD</sub> clamp voltage	I <sub>DD</sub> = 15 mA	23.5			V
V <sub>DDon</sub>	V <sub>DD</sub> start up threshold		12	13	14	V
V <sub>DDCSon</sub>	VDD on internal high voltage current generator threshold		9.5	10.5	11.5	V
V <sub>DDoff</sub>	V <sub>DD</sub> under voltage shutdown threshold		7	8	9	V
Current				1	1	1
I <sub>DD0</sub>	Operating supply current, not switching	F <sub>OSC</sub> = 0 kHz, V <sub>COMP</sub> = GND			0.6	mA
I	Operating supply current,	$V_{DRAIN}$ = 120 V, F <sub>SW</sub> = 60 kHz			2.5	mA
I <sub>DD1</sub>	switching	V <sub>DRAIN</sub> = 120 V, F <sub>SW</sub> = 115 kHz			3.5	mA
I <sub>DDoff</sub>	Operating supply current with $V_{DD} < V_{DDoff}$	V <sub>DD</sub> < V <sub>DDoff</sub>			0.35	mA
I <sub>DDol</sub>	Open loop failure current threshold	$V_{DD} = V_{DDclamp}$ $V_{COMP} = 3.3 V,$	4			mA

a. Adjust  $V_{\text{DD}}$  above  $V_{\text{DDon}}$  startup threshold before setting to 14 V



#### Table 8.Controller section

Table 8.	Controller section					
Symbol	Parameter	Test condition	Min	Тур	Max	Unit
Error amplifi	er		•			
V <sub>REF_FB</sub>	FB reference voltage		3.2	3.3	3.4	V
I <sub>FB_PULL UP</sub>	Current pull up			-1		μA
G <sub>M</sub>	Trans conductance			2		mA/V
Current setti	ng (LIM) pin				1	1
V <sub>LIM_LOW</sub>	Low level clamp voltage	I <sub>LIM</sub> = -100 μA		0.5		V
Compensatio	on (COMP) pin					
V <sub>COMPH</sub>	Upper saturation limit	T <sub>J</sub> = 25 °C		3		V
V <sub>COMPL</sub>	Burst mode threshold	T <sub>J</sub> = 25 °C	1	1.1	1.2	V
V <sub>COMPL_HYS</sub>	Burst mode hysteresis	T <sub>J</sub> = 25 °C		40		mV
H <sub>COMP</sub>	ΔV <sub>COMP</sub> / ΔI <sub>DRAIN</sub>			3		V/A
R <sub>COMP(DYN)</sub>	Dynamic resistance	V <sub>FB</sub> = GND		15		kΩ
I	Source / sink current	V <sub>FB</sub> > 100 mV		150		μA
ICOMP	Max source current	$V_{COMP} = GND, V_{FB} = GND$		220		μA
Current limit	ation					
I <sub>Dlim</sub>	Drain current limitation	$I_{LIM}$ = -10 $\mu$ A, $V_{COMP}$ = 3.3 V, $T_{J}$ = 25 °C	0.66	0.7	0.74	Α
t <sub>SS</sub>	Soft-start time			8.5		ms
T <sub>ON_MIN</sub>	Minimum turn ON time				480	ns
I <sub>Dlim_bm</sub>	Burst mode current limitation	V <sub>COMP</sub> = V <sub>COMPL</sub>		145		mA
Overload						
t <sub>OVL</sub>	Overload time			50		ms
t <sub>RESTART</sub>	Restart time after fault			1		S
Oscillator se	ction					
_		VIPER26L	54	60	66	kHz
F <sub>OSC</sub>	Switching frequency	VIPER26H	103	115	127	kHz
		F <sub>OSC</sub> = 60 kHz		±4		kHz
F <sub>D</sub>	Modulation depth	F <sub>OSC</sub> = 115 kHz		±8		kHz
F <sub>M</sub>	Modulation frequency			230		Hz
D <sub>MAX</sub>	Maximum duty cycle		70		80	%
Thermal shu	tdown			•		-
T <sub>SD</sub>	Thermal shutdown temperature		150	160		°C
T <sub>HYST</sub>	Thermal shutdown hysteresis			30		°C



#### **Typical electrical characteristics** 5









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**Operating supply current** 

Figure 10. I<sub>COMP</sub> vs T<sub>J</sub>



Figure 11.

Figure 13. IDlim vs R<sub>LIM</sub>

Figure 12. Operating supply current (switching) vs T<sub>J</sub>



Figure 14. Power MOSFET on-resistance vs  $T_{\rm J}\,$  Figure 15. Power MOSFET break down voltage vs  $T_{\rm J}\,$ 







Figure 16. Thermal shutdown

#### **Typical circuits** 6















Figure 20. Flyback converter (non isolated,  $V_{OUT} M V_{DDCSon}$ )





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### 7 Power section

The power section is implemented with an n-channel power MOSFET with a breakdown voltage of 800 V min. and a typical  $R_{DS(on)}$  of 7  $\Omega$  It includes a SenseFET structure to allow a virtually lossless current sensing and the thermal sensor.

The gate driver of the power MOSFET is designed to supply a controlled gate current during both turn-ON and turn-OFF in order to minimize common mode EMI. During UVLO conditions, an internal pull-down circuit holds the gate low in order to ensure that the power MOSFET cannot be turned ON accidentally.

## 8 High voltage current generator

The high voltage current generator is supplied by the DRAIN pin. At the first start up of the converter, it is enabled when the voltage across the input bulk capacitor reaches the  $V_{DRAIN\_START}$  threshold, sourcing the  $I_{DDch1}$  current (see *Table 7 on page 6*); as the  $V_{DD}$  voltage reaches the  $V_{DDon}$  start-up threshold, the power section starts switching and the high voltage current generator is turned OFF. The VIPer26 is powered by the external source. After the start-up, the auxiliary winding or the diode connected to the output voltage have to power the VDD capacitor with voltage higher than  $V_{DDCSon}$  threshold (see *Table 7 on page 6*). During the switching, the internal current source is disabled and the consumptions are minimized. In case of fault the switching is stopped and the device is self biased by the internal high voltage current  $I_{DDch2}$  to the  $V_{DD}$  capacitor during the MOSFET off time, see *Figure 22 on page 13*.

At converter power-down, the  $V_{DD}$  voltage drops and the converter activity stops as it falls below  $V_{DDoff}$  threshold (see *Table 7 on page 6*).







### 9 Oscillator

The switching frequency is internally fixed at 60 kHz (VIPER26LN or LD) or 115 kHz (VIPER26HN or HD).

In both cases the switching frequency is modulated by approximately  $\pm 4$  kHz (60 kHz version) or  $\pm 8$  kHz (115 kHz version) at 230 Hz (typical) rate, so that the resulting spread-spectrum action distributes the energy of each harmonic of the switching frequency over a number of sideband harmonics having the same energy on the whole but smaller amplitudes.

### 10 Soft start-up

During the converters' start-up phase, the soft-start function progressively increases the cycle-by-cycle drain current limit, up to the default value  $I_{Dlim}$ . By this way the drain current is further limited and the output voltage is progressively increased reducing the stress on the secondary diode. The soft-start time is internally fixed to  $t_{SS}$ , see typical value on *Table 8 on page 7*, and the function is activated for any attempt of converter start-up and after a fault event.

This function helps prevent transformers' saturation during start-up and short-circuit.

### 11 Adjustable current limit set point

The VIPer26 includes a current mode PWM controller: cycle by cycle the drain current is sensed through the integrated resistor R<sub>SENSE</sub> and the voltage is applied to the non inverting input of the PWM comparator, see *Figure 2 on page 3*. As soon as the sensed voltage is equal to the voltage derived from the COMP pin, the power MOSFET is switched OFF.

In parallel with the PWM operations, the comparator OCP, see *Figure 2 on page 3*, checks the level of the drain current and switch OFF the power MOSFET in case the current is higher than the threshold I<sub>Dlim</sub>, see *Table 8 on page 7*.

The level of the drain current limit,  $I_{Dlim}$ , can be reduced depending from the sunk current from the pin LIM. The resistor  $R_{LIM}$ , between LIM and GND pins, fixes the current sunk and than the level of the current limit,  $I_{Dlim}$ , see *Figure 13 on page 9*.

When the LIM pin is left open or if the  $R_{LIM}$  has an high value (i.e. > 80 k $\Omega$ ) the current limit is fixed to its default value,  $I_{Dlim}$ , as reported on *Table 8 on page 7*.



## 12 FB pin and COMP pin

The device can be used both in non-isolated and in isolated topology. In case of nonisolated topology, the feedback signal from the output voltage is applied directly to the FB pin as inverting input of the internal error amplifier having the reference voltage, V<sub>REF\_FB</sub>, see the *Table 8 on page 7*.

The output of the error amplifier sources and sinks the current,  $I_{COMP}$  respectively to and from the compensation network connected on the COMP pin. This signal is then compared, in the PWM comparator, with the signal coming from the SenseFET; the power MOSFET is switched off when the two values are the same on cycle by cycle basis. See the *Figure 2 on page 3* and the *Figure 23 on page 15*.

When the power supply output voltage is equal to the error amplifier reference voltage,  $V_{\text{REF}_FB}$ , a single resistor has to be connected from the output to the FB pin. For higher output voltages the external resistor divider is needed. If the voltage on FB pin is accidentally left floating, an internal pull-up protects the controller.

The output of the error amplifier is externally accessible through the COMP pin and it's used for the loop compensation: usually an RC network.

As reported on *Figure 23 on page 15*, in case of isolated power supply, the internal error amplifier has to be disabled (FB pin shorted to GND). In this case an internal resistor is connected between an internal reference voltage and the COMP pin, see the *Figure 23 on page 15*. The current loop has to be closed on the COMP pin through the opto-transistor in parallel with the compensation network. The V<sub>COMP</sub> dynamics ranges is between V<sub>COMPL</sub> and V<sub>COMPH</sub> as reported on *Figure 24 on page 16*.

When the voltage  $V_{COMP}$  drops below the voltage threshold  $V_{COMPL}$ , the converter enters burst mode, see *Section 13 on page 16*.

When the voltage  $V_{COMP}$  rises above the  $V_{COMPH}$  threshold, the peak drain current will reach its limit, as well as the deliverable output power



Figure 23. Feedback circuit





Figure 24. COMP pin voltage versus IDLIM

### 13 Burst mode

When the voltage  $V_{COMP}$  drops below the threshold,  $V_{COMPL}$ , the power MOSFET is kept in OFF state and the consumption is reduced to  $I_{DD0}$  current, as reported on *Table 7 on page 6*. As reaction at the energy delivery stop, the  $V_{COMP}$  voltage increases and as soon as it exceeds the threshold  $V_{COMPL} + V_{COMPL_HYS}$ , the converter starts switching again with consumption level equal to  $I_{DD1}$  current. This ON-OFF operation mode, referred to as "burst mode" and reported on *Figure 25 on page 16*, reduces the average frequency, which can go down even to a few hundreds hertz, thus minimizing all frequency-related losses and making it easier to comply with energy saving regulations. During the burst mode, the drain current limit is reduced to the value  $I_{Dlim_bm}$  (reported on *Table 8 on page 7*) in order to avoid the audible noise issue.



Figure 25. Load-dependent operating modes: timing diagrams



## 14 Automatic auto restart after overload or short-circuit

The overload protection is implemented in automatic way using the integrated up-down counter. Every cycle, it is incremented or decremented depending if the current logic detects the limit condition or not. The limit condition is the peak drain current,  $I_{Dlim}$ , reported on *Table 8 on page 7* or the one set by the user through the R<sub>LIM</sub> resistor, as reported in *Figure 13 on page 9*.

After the reset of the counter, if the peak drain current is continuously equal to the level  $I_{Dlim}$ , the counter will be incremented till the fixed time,  $t_{OVL}$ , after that will be disabled the power MOSFET switch ON. It will be activated again, through the soft start, after the  $t_{RESTART}$  time, see the *Figure 26 on page 17* and the mentioned time values on *Table 8 on page 7*.

In case of overload or short-circuit event, the power MOSFET switching will be stopped after a time that depends from the counter and that can be as maximum equal to  $t_{OVL}$ . The protection will occur in the same way until the overload condition is removed, see *Figure 26* on page 17.

This protection ensures restart attempts of the converter with low repetition rate, so that it works safely with extremely low power throughput and avoiding the IC overheating in case of repeated overload events.

If the overload is removed before the protection tripping, the counter will be decremented cycle by cycle down to zero and the IC will not be stopped.



#### Figure 26. Timing diagram: OLP sequence



### 15 Open loop failure protection

In case the power supply is built in fly-back topology and the VIPer26 is supplied by an auxiliary winding, as shown in *Figure 27 on page 18* and *Figure 28 on page 19*, the converter is protected against feedback loop failure or accidental disconnections of the winding.

The following description is applicable for the schematics of *Figure 27 on page 18* and *Figure 28 on page 19*, respectively the non-isolated fly-back and the isolated fly-back.

If  $R_H$  is opened or  $R_L$  is shorted, the VIPer26 works at its drain current limitation. The output voltage,  $V_{OUT}$ , will increase and so the auxiliary voltage,  $V_{AUX}$ , which is coupled with the output through the secondary-to-auxiliary turns ratio.

As the auxiliary voltage increases up to the internal  $V_{DD}$  active clamp,  $V_{DDclamp}$  (the value is reported on *Table 8 on page 7*) and the clamp current injected on VDD pin exceeds the latch threshold,  $I_{DDol}$  (the value is reported on *Table 8 on page 7*), a fault signal is internally generated.

In order to distinguish an actual malfunction from a bad auxiliary winding design, both the above conditions (drain current equal to the drain current limitation and current higher than  $I_{DDol}$  through VDD clamp) have to be verified to reveal the fault.

If  $R_L$  is opened or  $R_H$  is shorted, the output voltage,  $V_{OUT}$ , will be clamped to the reference voltage  $V_{REF\_FB}$  (in case of non isolated fly-back) or to the external TL voltage reference (in case of isolated fly-back).



Figure 27. FB pin connection for non-isolated fly-back





Figure 28. FB pin connection for isolated fly-back



## 16 Package mechanical data

In order to meet environmental requirements, ST offers these devices in different grades of ECOPACK<sup>®</sup> packages, depending on their level of environmental compliance. ECOPACK<sup>®</sup> specifications, grade definitions and product status are available at: www.st.com. ECOPACK<sup>®</sup> is an ST trademark.

Dim.		mm	
Dini.	Тур	Min	Мах
А			5.33
A1		0.38	
A2	3.30	2.92	4.95
b	0.46	0.36	0.56
b2	1.52	1.14	1.78
С	0.25	0.20	0.36
D	9.27	9.02	10.16
E	7.87	7.62	8.26
E1	6.35	6.10	7.11
е	2.54		
eA	7.62		
eB			10.92
L	3.30	2.92	3.81
М	2.508		
Ν	0.50	0.40	0.60
N1			0.60
0	0.548		

Table 9. DIP-7 mechanical data







Figure 29. DIP-7 package dimensions



Dim		mm	
Dim.	Min	Тур	Мах
А			1.75
A1	0.1		0.25
A2	1.25		
b	0.31		0.51
С	0.17		0.25
D	9.8	9.9	10
E	5.8	6	6.2
E1	3.8	3.9	4
е		1.27	
h	0.25		0.5
L	0.4		1.27
k	0		8
ccc			0.1

Table 10. SO16N mechanical data

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Figure 30. SO16N package dimensions



# 17 Revision history

### Table 11. Document revision history

Date	Revision	Changes
26-Aug-2010	1	Initial release.
01-Sep-2010	2	Updated Figure 30 on page 23.



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